

**IN THE CLAIMS:**

*Please amend the claims as follows:*

1. *(currently amended)* A method for analysing connection conditions between an integrated circuit package and a circuit board,
  - wherein said integrated circuit package is electrically coupled to said circuit board by coupling elements, and
  - wherein said integrated circuit package is mechanically connected with said circuit board by support elements, characterised in that
  - said support elements are electrically connected to each other on the side of the integrated circuit package,
  - physical values are picked-off from said support elements, and
  - said physical values are evaluated to determine the condition of said connection between said integrated circuit package and said circuit board.
2. *(original)* The method of claim 1, wherein electrical values are picked-off from said support elements.
3. *(original)* The method of claim 1, wherein electrical resistance and/or electrical current and/or voltage within said support elements is picked-off.
4. *(original)* The method of claim 1, wherein mechanical values are picked-off from said support elements.
5. *(original)* The method of claim 1, wherein mechanical values are picked-off from said support elements using a strain gauge.

6. *(original)* The method of claim 1, wherein a condition of said electrical coupling of said integrated circuit package with said circuit board is concluded from said determined condition of said connection.
7. *(original)* The method of claim 1, wherein said connection condition is determined in intervals.
8. *(original)* The method of claim 1, wherein said determined connection conditions are stored.
9. *(original)* The method of claim 1, wherein in case a poor connection condition is determined, a error message is generated.
10. *(original)* The method of claim 9, wherein said error message is presented on a user interface.
11. *(original)* The method of claim 9, wherein said error message is stored.
12. *(original)* The method of claim 9, wherein said error message is read out from a storage and used for maintenance.
13. *(currently amended)* A system for analysing connection conditions between an integrated circuit package and a circuit board, comprising:
  - coupling elements coupling said integrated circuit package electrically to said circuit board, and
  - support elements connecting said integrated circuit package mechanically with said circuit board,

characterised by

- electrically connecting said support elements on the side of the integrated circuit package,
- measuring means arranged at said support elements to pick-off physical values from said support elements, and
- evaluation means evaluating said physical values to determine the condition of said connection between said integrated circuit package and said circuit board.

14. *(original)* The system of claim 13, wherein said support elements are arranged between said circuit board and said integrated circuit package.
15. *(original)* The system of claim 13, wherein said support elements are solder pads.
16. *(original)* The system of claim 13, wherein said support elements are arranged adjacent to said coupling elements.
17. *(original)* The system of claim 13, wherein said support elements are arranged semicircular along said coupling elements.
18. *(original)* The system of claim 13, wherein said support elements are arranged along edges and/or at corners of said integrated circuit package.
19. *(original)* The system of claim 13, wherein said integrated circuit package is a chip scale package or a chip size package.
20. *(original)* The system claim 13, wherein said measuring means provide picking-off electrical conditions of said support elements.

21. *(original)* The system claim 13, wherein said measuring means provide picking-off mechanical conditions of said support elements.
22. *(original)* The system of claim 13, wherein storage means are comprised to store said picked-off physical values.
23. *(original)* The system of claim 13, wherein said evaluation means compare said picked-off physical values with comparative values to determine connection condition.
24. *(original)* The system of claim 13, wherein said evaluation means provide an error message in case a poor connection condition is determined.
25. *(original)* The system of claim 13, wherein said error message is stored within said storage means.
26. *(original)* The system of claim 13, wherein an interface is provided to read out said stored physical values and/or stored error messages.
27. *(original)* Consumer electronic device, in particular a mobile phone, comprising a system of claim 13.
28. *(original)* Computer program operable to cause a processor to analyse connection conditions between an integrated circuit package and a circuit board according to a method of claim 1.
29. *(original)* Computer program product comprising a computer program operable to cause a processor to analyse connection conditions between an integrated circuit package and a circuit board according to a method of claim 1.